
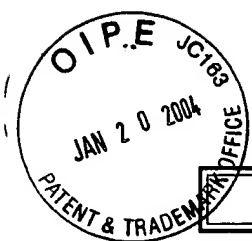


ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention	PLANARIZED SEMICONDUCTOR INTERCONNECT TOPOGRAPHY AND METHOD FOR POLISHING A METAL LAYER TO FORM INTERCONNECT																												
<p>Application Number: 09/779123 </p> <p>Confirmation Number: 9269</p> <p>First Named Applicant: Anantha Sethuraman</p> <p>Attorney Docket Number: 5298-02502</p> <p>Art Unit: 2823</p> <p>Examiner: Hsien-Ming Lee</p> <p>Search string: (5958794 or 5972124).pn.</p> <p>US Patent Documents</p> <p>Note: Applicant is not required to submit a paper copy of cited US Patent Documents</p> <table border="1"><thead><tr><th>init</th><th>Cite.No.</th><th>Patent No.</th><th>Date</th><th>Patentee</th><th>Kind</th><th>Class</th><th>Subclass</th></tr></thead><tbody><tr><td></td><td>1</td><td>5958794</td><td>1999-09-28</td><td>Bruxvoort et al.</td><td></td><td></td><td></td></tr><tr><td></td><td>2</td><td>5972124</td><td>1999-10-26</td><td>Sethuraman et al.</td><td></td><td></td><td></td></tr></tbody></table> <p>Signature</p> <table border="1"><thead><tr><th>Examiner Name</th><th>Date</th></tr></thead><tbody><tr><td></td><td></td></tr></tbody></table>		init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass		1	5958794	1999-09-28	Bruxvoort et al.					2	5972124	1999-10-26	Sethuraman et al.				Examiner Name	Date		
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Examiner Name	Date																												

**FEE TRANSMITTAL**

Electronic Version v08
Stylesheet Version v08.0


Title of Invention	PLANARIZED SEMICONDUCTOR INTERCONNECT TOPOGRAPHY AND METHOD FOR POLISHING A METAL LAYER TO FORM INTERCONNECT										
Application Number: 09/779123 											
Date: 2001-02-07											
First Named Applicant: Anantha R. Sethuraman											
Attorney Docket Number: 5298-02502											
Art Unit: 2823											
Examiner: Hsien-Ming Lee											
TOTAL FEE AUTHORIZED \$180											
Patent fees are subject to annual revisions on or about October 1st of each year.											
BASIC FILING FEE											
<table border="1"><thead><tr><th>Fee Description</th><th>Fee Code</th><th>Amount \$</th><th>Fee Paid \$</th></tr></thead><tbody><tr><td>Submission Of Information Disclosure Stmt Fee</td><td>1806</td><td>180</td><td>180</td></tr></tbody></table>				Fee Description	Fee Code	Amount \$	Fee Paid \$	Submission Of Information Disclosure Stmt Fee	1806	180	180
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Submission Of Information Disclosure Stmt Fee	1806	180	180								
AUTHORIZED BILLING INFORMATION											
The commissioner is hereby authorized to charge indicated fees and credit any overpayments to:											
Deposit account number: 032769											
Access Code ****											
Deposit name: Conley Rose, P.C.											
Deposit authorized name: Kevin L. Daffer											
Signature: Kevin L. Daffer											
Date (YYYYMMDD): 2004-01-20											



Electronic Filing System (EFS) Data
Electronic Patent Application Submission
USPTO Use Only

1FW

EFS ID: 53978

Application ID: 09779123 

Title of Invention: PLANARIZED SEMICONDUCTOR
INTERCONNECT TOPOGRAPHY
AND METHOD FOR POLISHING A
METAL LAYER TO FORM
INTERCONNECT

First Named Inventor: Anantha Sethuraman

Domestic/Foreign Application: Domestic Application

Filing Date: 2001-02-07

Effective Receipt Date: 2004-01-20

Submission Type: Information Disclosure
Statement

Filing Type:

Confirmation number: 9269

Attorney Docket Number: 5298-02502

Total Fees Authorized: 180.0

Payment Category: Deposit Account

Deposit Account Number: 32769

Deposit Account Name: Kevin L. Daffer

Access Code: ****

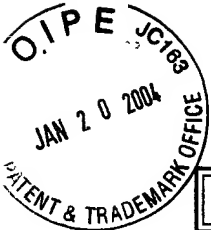
RAM Payment Status: RAM success

RAM User ID: EFSPROD

RAM Accounting Date: 2004-01-20

RAM Sequence Number: 4


Digital Certificate Holder: cn=Kevin L. Daffer,ou=Registered Attorneys,ou=Patent and Trademark
Office,ou=Department of Commerce,o=U.S. Government,c=US
Certificate Message Digest: 9099fb8e14cf0e12f779738052769534f3ce595c



TRANSMITTAL

Electronic Version v1.1

Stylesheet Version v1.1.0

Title of Invention	PLANARIZED SEMICONDUCTOR INTERCONNECT TOPOGRAPHY AND METHOD FOR POLISHING A METAL LAYER TO FORM INTERCONNECT															
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<p>I hereby certify that the use of this system is for OFFICIAL correspondence between patent applicants or their representatives and the USPTO. Fraudulent or other use besides the filing of official correspondence by authorized parties is strictly prohibited, and subject to a fine and/or imprisonment under applicable law.</p> <p>I, the undersigned, certify that I have viewed a display of document(s) being electronically submitted to the United States Patent and Trademark Office, using either the USPTO provided style sheet or software, and that this is the document(s) I intend for initiation or further prosecution of a patent application noted in the submission. This document(s) will become part of the official electronic record at the USPTO.</p>																
<table border="1"><tr><td>Submitted by:</td><td>Elec. Sign.</td><td>Sign. Capacity</td></tr><tr><td>Kevin L. Daffer Registered Number: 34146</td><td>Kevin L. Daffer</td><td>Attorney</td></tr></table>			Submitted by:	Elec. Sign.	Sign. Capacity	Kevin L. Daffer Registered Number: 34146	Kevin L. Daffer	Attorney								
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Comments
